



**FOR IMMEDIATE RELEASE**

**HDP User Group Announces Free Automotive Electronics Webinar**

*Cave Creek, Arizona May 19, 2020.* High-Density Packaging (HDP) User Group is pleased to announce it is hosting a webinar that will provide its members and others in the electronic industry the latest information on standard requirements and developments in automotive electronics.

"Automotive Electronics is one of the fastest-growing segments of advanced electronics technology. We have planned an informational session that will cover the latest developments in automotive standards and automotive electronic packaging", said Marshall Andrews, Executive Director of HDP User Group.

The Webinar will be held on June 25, 2020, at 8 AM USA Central Time.

**Agenda 8:00 AM – 11:00 AM US Central Time**

**Welcome** – Larry Marcanti, HDP

**Opening of the Webinar by the Moderator**

Jan Vardeman, President, and Founder of Techsearch International recognized around the world as a leading consulting company in the field of advanced semiconductor packaging technology.

**Mobility Trends and Their Impact on The Automotive Supply Chain**

- ZVEI – DR Stefan.Gutschling

**Power PCB requirements for Automotive Applications**

- Ventec Laminates – Alun Morgan

**Automotive Packaging Trends – Challenges & Solutions**

- Infineon – Thorsten Meyer

**The regulatory landscape for vehicle electronics and primary evaluation tools for PCB reliability demands in the new e-mobility market.**

- UL – Art Creidler

**Considerations in Automotive PCB manufacture**

- TTM – Raj Kumar

**Round Table & Questions**

**Webinar Close**



## Technology Development in Today's Global Environment

[www.hdpug.org](http://www.hdpug.org)

The Webinar is in the English language.

Please register for webinar log-in and call details by emailing your contact info (name, Company Info, Email) to one the following people.

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### **About HDP User Group**

HDP User Group ([www.hdpug.org](http://www.hdpug.org)) is a global research and development organization based in Cave Creek Arizona, which is dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly.” This international industry-led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas, and Singapore.

For more information, visit HDP User Group on the Internet at [www.hdpug.org](http://www.hdpug.org) or contact Darryl Reiner at [darrylr@hdpug.org](mailto:darrylr@hdpug.org), phone number +1 480-951-1963